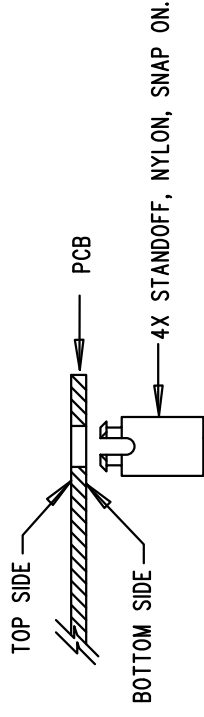
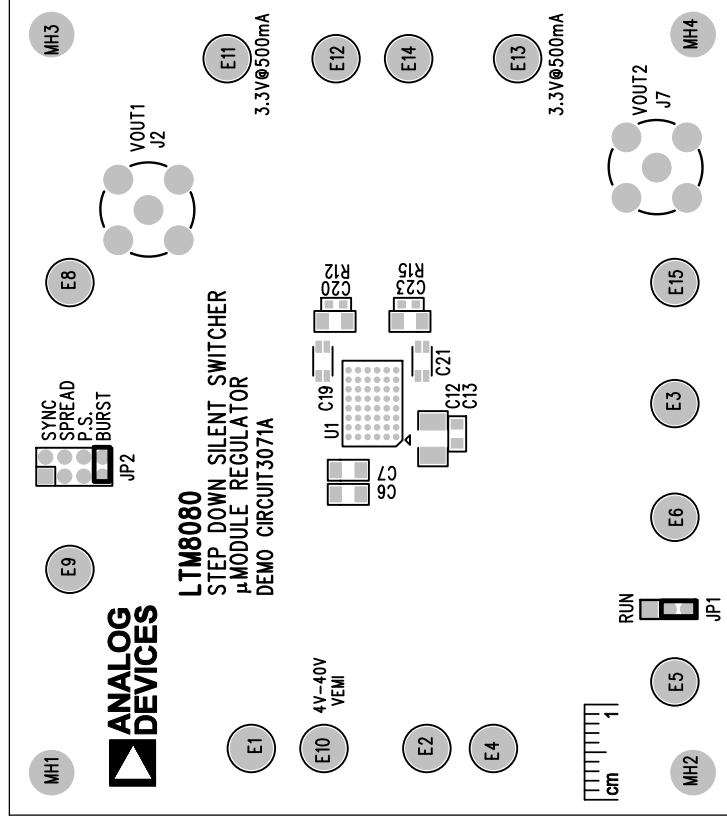
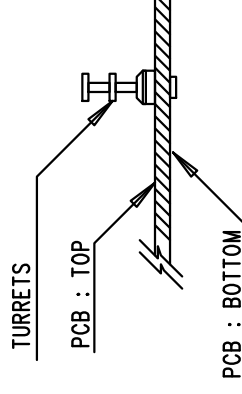


NOTES: UNLESS OTHERWISE SPECIFIED


1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



8. INSTALL TURRETS AS SHOWN BELOW:



TOP SILKSCREEN

APPROVALS		 ANALOG DEVICES			
PCB DES.	HZ				
APP ENG.	SG				
		TITLE: TOP ASSEMBLY DRAWING STEP DOWN SILENT SWITCHER μMODULE REGULATOR			
		SIZE	IC NO.	LTM8080	REV.
		N/A	DEMO CIRCUIT	3071A	1
SCALE = NONE		FILENAME: DC3071A.PCB			SHT 1 OF 2